



Chen 29-3-4
LU05003USU

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Chen, Young-Kai et al.

Serial No.: 10/628,748

Filed: July 28, 2003

For: CONDUCTIVE ISOLATION FRAMES FOR ACTIVE MICROELECTRONIC
DEVICES, AND METHODS OF MAKING SUCH CONDUCTIVE ISOLATION
FRAMES

Group: 2814

Confirmation: 4860

Examiner: Steven H. Rao

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:
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Signed: Bonnie S. Sheridan Name: Bonnie S. Sheridan Date: November 28, 2005

Durham, North Carolina
November 28, 2005

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Amendment in Response to Office Action Mailed on July 26, 2005

Sir:

Please amend the present application as follows:

In the Title:

Please amend the Title as follows:

DISSIPATIVE CONDUCTIVE ISOLATION FRAMES FOR ACTIVE MICROELECTRONIC
DEVICES, AND METHODS OF MAKING SUCH DISSIPATIVE CONDUCTIVE
ISOLATION FRAMES